

# UTF3055

# N-CHANNEL ENHANCEMENT MODE POWER MOSFET

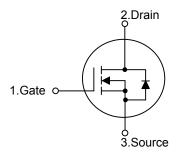
## DESCRIPTION

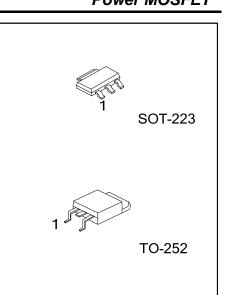
As an N-channel enhancement mode power MOSFET, the UTC **UTF3055** is designed for low voltage, high speed switching applications in power supplies, converters and power motor controls and bridge circuits.

### FEATURES

\*  $R_{DS(ON)}$  < 110 m $\Omega$  @V<sub>GS</sub>=10V

SYMBOL

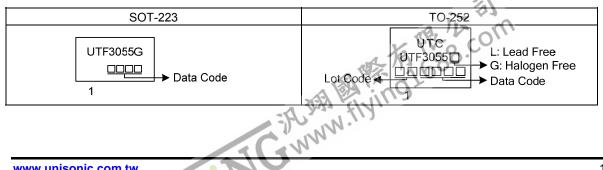




#### ORDERING INFORMATION

1						1	
Ordering Number		Dookogo	Pin Assignment			Decking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
-	UTF3055G-AA3-R	SOT-223	G	D	S	Tape Reel	
UTF3055L-TN3-R	UTF3055L-TN3-R UTF3055G-TN3-R		G	D	S	Tape Reel	
Note: Pin Assignment: S: Source G: Gate D: Drain							
UTF3055G-AA3-R		(1) R: Tape Reel					
(2)Package Type (3)Green Package		(2) AA3: SOT-223, TN3: TO-252					
		(3) G: Halogen Free and Lead Free, L:Lead Free					

#### MARKING



# **Power MOSFET**

#### ■ ABSOLUTE MAXIMUM RATINGS (T<sub>c</sub> =25°C, unless otherwise noted)

PARAMETER		SYMBOL	RATINGS	UNIT		
Drain Source Voltage		V <sub>DSS</sub>	60	V		
Drain Gate Voltage ( $R_{GS}$ = 10M $\Omega$ )		V <sub>DGR</sub>	60	V		
Cata Sauraa Maltara	Continuous		N	±20	V	
Gate Source Voltage	on-Repetitive	(t <sub>P</sub> ≤10 ms)	V <sub>GSS</sub>	±30	V	
Continuous Drain Current (	Continuous Drain Current ( $T_a = 25^{\circ}C$ )		ID	3.0	А	
Pulsed Drain Current (t <sub>P</sub> ≤10 µs)		I <sub>DM</sub>	9.0	А		
Single Pulsed Avalanche Energy (Note 2)		EAS	74	mJ		
Power Dissipation (T <sub>a</sub> = 25°C) (Note 3)		SOT-223		0.83	14/	
		TO-252		1.136	W	
Derate above 25°C		SOT-223	PD	14	mW/°C	
		TO-252		20		
Junction Temperature		TJ	175	°C		
Strong Temperature		T <sub>STG</sub>	-55 ~ +175	°C		

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2.  $T_J = 25^{\circ}C$  ,  $V_{DD} = 25V$ ,  $V_{GS} = 10V$ ,  $I_L = 7.0A$ , L = 3.0mH,  $V_{DS} = 60V$ 

3. When surface mounted to an FR4 board using 1'' pad size, 1 oz. (Cu. Area 1.127 sq in ).

#### THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient (Note)	SOT-223	0.14	150	°C/W
	TO-252	θJA	110	°C/W

Note: When surface mounted to an FR4 board using 1" pad size, 1 oz. (Cu. Area 1.127 sq in ).



#### ■ ELECTRICAL CHARACTERISTICS (T<sub>J</sub> =25°C, unless otherwise noted)

				-		-
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain Source Breakdown Voltage (Note 1)	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250µA	60	68		V
Temperature Coefficient (Positive)	DVDSS			66		mV/°C
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =60V			1.0	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{GS}$ = ±20 V, $V_{DS}$ =0V			±100	nA
ON CHARACTERISTICS (Note 1)						
Gate Threshold Voltage	V	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250µA	2.0	3.0	4.0	V
Temperature Coefficient (Negative)	V <sub>GS(TH)</sub>			6.6		mV/°C
Static Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =1.5A		88	110	mΩ
Static Drain-to-Source On-Resistance	V <sub>DS(ON)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =3A		0.27	0.40	V
Forward Tran conductance	<b>g</b> fs	V <sub>DS</sub> =8.0V, I <sub>D</sub> =1.7A		3.2		М
DYNAMIC PARAMETERS						
Input Capacitance	CISS			324	455	pF
Output Capacitance	C <sub>OSS</sub>	V <sub>GS</sub> =0 V, V <sub>DS</sub> =25 V, f=1.0MHz		35	50	pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			110	155	рF
SWITCHING PARAMETERS (Note 2)						
Turn-ON Delay Time	t <sub>D(ON)</sub>			9.4	20	ns
Turn-ON Rise Time	t <sub>R</sub>	V <sub>GS</sub> =10V, V <sub>DD</sub> =30V, I <sub>D</sub> =3.0A ,		14	30	ns
Turn-OFF Delay Time	t <sub>D(OFF)</sub>	R <sub>G</sub> =9.1Ω (Note 1)		21	45	ns
Turn-OFF Fall-Time	t <sub>F</sub>			13	30	ns
Total Gate Charge	$Q_{G}$			10.6	22	nC
Gate-Source Charge	QGS	$V_{GS} = 10V, V_{DS} = 48V, I_D = 3.0A$		1.9		nC
Gate-Drain Charge	QGD	(Note 1)		4.2		nC
Diode Forward Voltage	$V_{SD}$	V <sub>GS</sub> =0V, I <sub>S</sub> =3.0A		0.89	1.0	V
	t <sub>RR</sub>			30		ns
Body Diode Reverse Recovery Time	t <sub>A</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =3.0A,		22		ns
	t <sub>B</sub>	dl/dt=100 A/µs (Note 1)		8.6		ns
Body Diode Reverse Recovery Charge	$Q_{RR}$			0.04		nC

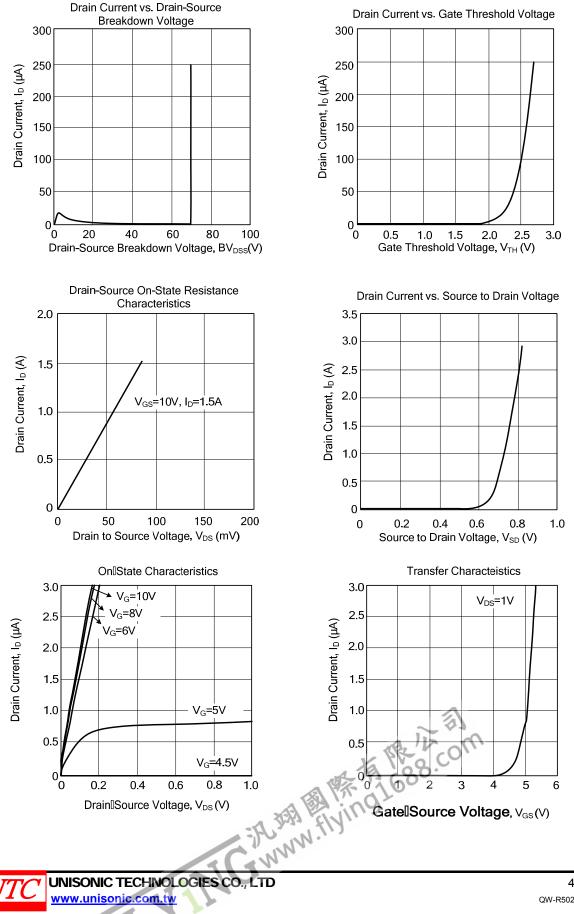
Notes: 1. Pulse Test : Pulse width ≤300µs, Duty cycle ≤2%.

2. Switching characteristics are independent of operating junction temperatures.

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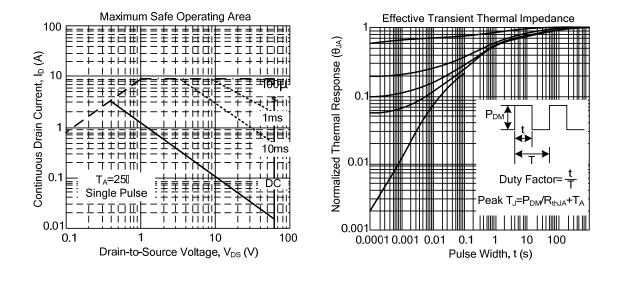
# **UTF3055**

## TYPICAL CHARACTERISTICS



# UTF3055

## **TYPICAL CHARACTERISTICS (Cont.)**



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